

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	JP\$'06085510'\$	JPO	ADJ	ON	2008/06/09 06:11
L2	13534	((29/846,847,852,600,501,825,829,830,831,832,25,42,25,02,25,03) or (343/773,776,778) or (333/239,248)).CCLS	US-PGRUB; USPAT	OR	OFF	2008/06/09 06:56
L3	685	l2 and @pd> "20071101"	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/09 06:57
L4	367	l3 and (etched or etching)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/09 06:57
S1	1	("5652557").PN.	US-PGRUB; USPAT	OR	OFF	2008/06/05 16:26
S2	1401	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:38
S3	387	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process). drwd.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:39
S4	199	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process). drwd. and substrate with (semiconduct\$)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:40
S5	230	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process). drwd. and substrate with (semiconduct\$3 or Si.m/c. or silicon)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:40
S6	393301	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process). drwd. and wafer or substrate with (semiconduct\$3 or Si.m/c. or silicon)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:40
S7	240	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process). drwd. and (wafer or substrate with (semiconduct\$3 or Si.m/c. or silicon))	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 16:41
S8	29115	(transmission line or waveguide or wave guide or wave-guide) and (method or process). drwd.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:25
S9	8055	(transmission line or waveguide or wave guide or wave-guide) and (method or process). drwd. and dielectric	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:26
S10	15015	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and (method or process).drwd.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:26
S11	2560	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and (method or process).drwd. and (etching or etched)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:29

S12	1378	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide).ti, ab,clm,bsum. and (method or process).drwd. and (etching or etched)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:30
S13	1238	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide).ti, ab,clm,bsum. and (method or process).drwd. and (etching or etched) not S7	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 17:31
S14	86	(dielectric waveguide or dielectric wave guide or dielectric wave-guide).ti,ab,clm,bsum. and (method or process).drwd. and (etching or etched) not S7	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/05 18:26
S15	171	(dielectric waveguide or dielectric wave guide or dielectric wave-guide) and (method or process)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 18:49
S16	1032	(dielectric waveguide or dielectric wave guide or dielectric wave-guide)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:05
S17	0	(dielectric waveguide or dielectric wave guide or dielectric wave-guide) not S16	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:05
S18	961	(dielectric waveguide or dielectric wave guide or dielectric wave-guide) not S15	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:05
S19	2709	h01p11/00.ipcr.	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:38
S20	4778	(h01p011/00).ipc. or h01p11/00.ipcr.	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:38
S21	31	S20 and (nonradiative or nonradiating or non-radiative or non-radiating)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:47
S22	919	S20 and (waveguide or wave guide or wave-guide)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/05 19:56
S23	809	(h01p011/00).ipc. or h01p11/00.ipcr.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 07:43

S24	4778	(h01p011/00).ipc. or h01p11/00.ipcr.	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/06 07:44
S25	919	S24 and (waveguide or wave guide or wave-guide)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/06 07:44
S26	717	S25 not us.cc.	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/06 07:44
S27	52	S24 and (guide) not us.cc. not S25	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/06 08:44
S28	777	(h01p011/00).ipc. or h01p11/00.ipcr.	US-PGRUB; USPAT	ADJ	ON	2008/06/06 09:05
S29	20586	(h01p\$/\$.).ipc. or h01p\$/\$.ipcr.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:00
S30	1306	S29 and (method or process).drwd.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:01
S31	387	(transmission line or dielectric waveguide or dielectric wave guide or dielectric wave-guide) and substrate with dielectric and (etched or etching) with dielectric and (method or process).drwd.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:02
S33	421	S29 and (method or process).drwd. not S31 and (etch or etching or etched)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:02
S34	784	S29 and (etch or etching or etched) with (dielectric or insulator or insulating)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:25
S35	310	S29 and (etch or etching or etched) with (dielectric or insulator or insulating) and (methor or process).ti.ab.bsum.clm.	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:26
S36	175	S29 and sacrificial	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/06 11:46
S37	4542	microstrip and (etched or etching)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:24
S38	0	microstrip.ti.ab.clm. and (etched or etching)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:25
S39	1558	microstrip.ti.ab.clm. and (etched or etching)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:25
S40	867	microstrip.ti.ab.clm. and (etched or etching) same dielectric	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:25

S41	702	microstrip.ti.ab,dm. and (etched or etching) same dielectric and (method or process)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:31
S42	285	microstrip.ti.ab,dm. and (etched or etching) same dielectric and (method or process) with microstrip	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 10:32
S44	331	transmission line.ti.ab,dm. and (etched or etching) same dielectric and (method or process) with transmission line not S42	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 12:21
S45	1	("7030721").PN.	US-PGRUB; USPAT	OR	OFF	2008/06/08 13:18
S46	121	first sacrificial and second sacrificial and (microstrip or waveguide or wave guide or transmission line)	US-PGRUB; USPAT; USOCR	ADJ	ON	2008/06/08 13:38
S47	4784	(h01p011/00).ipc. or h01p11/00.ipcr.	FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:06
S49	73	S47 and (waveguide or wave guide or wave-guide or transmission line or microstrip) and (etched or etching)	FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:07
S50	16	S47 and parallel plate	FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:16
S51	2344	S47 and dielectric	FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:18
S52	48	S47 and (transmission line or microstrip) and (etched or etching)	FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:18
S53	76	(nrd or nonradiative or non radiative or non-radiative) near2 (wave guide or wave-guide or wave guide or transmission line or microstrip)	US-PGRUB; USPAT; USOCR; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:23
S54	466	nrd guide	US-PGRUB; USPAT; USOCR; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 14:51

S55	61	(333/240).CCL.S.	US-PGPUB; USPAT	OR	OFF	2008/06/08 15:14
S56	387	(333/239).CCL.S.	US-PGPUB; USPAT	OR	OFF	2008/06/08 15:16
S57	4784	S47	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 15:32
S58	4784	S47	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/06/08 15:54
S59	1	1991-017651.NRAN.	DERWENT	ADJ	ON	2008/06/08 18:06
S60	1	("20050057326").PN.	US-PGPUB; USPAT	OR	OFF	2008/06/08 18:09
S61	112	"29".clas. and circuit board and photoresist with patterned same metal	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:19
S62	6	"29".clas. and circuit board and photoresist with patterned same metal and (microstrip)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:20
S63	113	circuit board and photoresist with pattern\$3 same metal and (microstrip)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:21
S64	648	photoresist with pattern\$3 same metal same cmp and semiconductor with substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:23
S65	322	photoresist with pattern\$3 same metal with deposit\$3 same cmp and semiconductor with substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:23
S66	139	photoresist with remov\$3 same photoresist with pattern\$3 same metal with deposit\$3 same cmp and semiconductor with substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/08 18:27
S67	1	("7067397").PN.	US-PGPUB; USPAT	OR	OFF	2008/06/08 19:25
S68	1	("6611237").PN.	US-PGPUB; USPAT	OR	OFF	2008/06/08 20:03

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